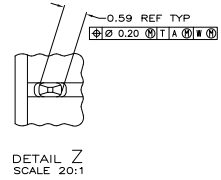
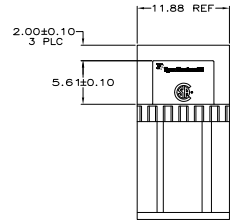
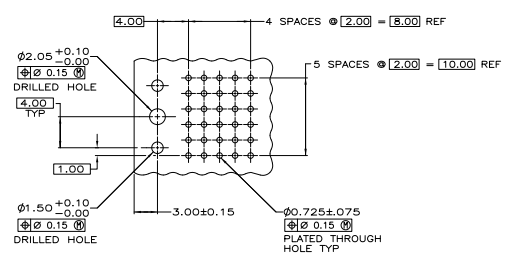
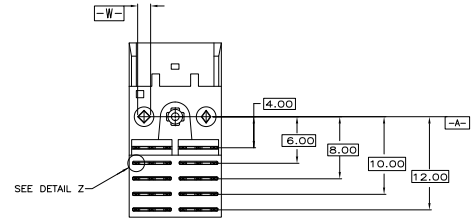
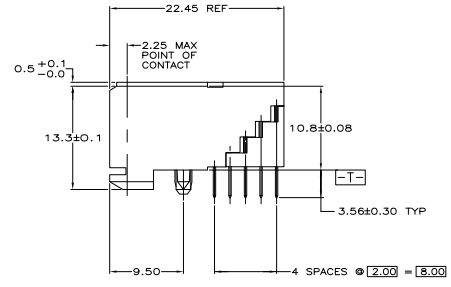
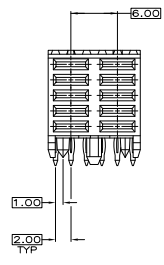


REV	DATE	DESCRIPTION	BY	CHK	APP
AD	00				
J1		REVISED PER ECO-08-009182	22APR08	DH	AS



△ HOUSINGS MATERIAL: LIQUID CRYSTAL POLYMER.  
 △ CONTACT MATERIAL: COPPER ALLOY  
 △ CONTACT FINISH:  
 UNDERPLATE (ENTIRE CONTACT):  
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290  
 ON MATING SURFACES:  
 FLASH GOLD PER ASTM B 488, OVER  
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR  
 0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.  
 ON LEADS:  
 0.00127 MIN TIN-LEAD OVER UNDERPLATE.  
 LUBRICATION (MIN MATING SURFACES):  
 SURFACE CONDITIONER AFTER PLATING.



RECOMMENDED CIRCUIT PATTERN  
 PER IPC-D300 TYPE II, CLASS C  
 (COMPONENT SIDE)

FINISH	536676-1
PART NUMBER	

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	5-20-08	BY	SHUEY
APPROVED	DESIGNED	DATE	5-23-08	BY	KONALICK
DATE	5-23-08	BY	KONALICK	DATE	5-23-08
PROJECT	RCPT ASSEMBLY, POWER_Z - PACK 2mm FB, R/A5 ROW, 10 POSN, W/TAIL ORGANIZER	DATE		BY	
SIZE	A1	DATE	00779	Q=536676	REV
CUSTOMER DRAWING		DATE	4-1	REV	J1